

**2016 INTERNATIONAL SYMPOSIUM ON
3D POWER ELECTRONICS INTEGRATION & MANUFACTURING**

	13-Jun-16 MONDAY	14-Jun-16 TUESDAY	15-Jun-16 WEDNESDAY
8:00 AM - 9:55 AM	TUTORIALS THE WORLD OF PACKAGING TECHNOLOGIES and THE CRITICAL ISSUES	PLENARY ROAD MAPPING Ernier Parker (Crane), Chair <i>Invited Speakers:</i> Chuck Richardson (iNEMI) Braham Ferrera (DELFT) Bill Chen (CPMT)	MANUFACTURABILITY Jared Hornberger (Wolfspeed), Chair <i>Keynote Invited Speakers:</i> TBA
9:55 AM - 10:20 PM	3D Power Electronics & Additive Mfg. by Dr Douglas Hopkins	Break	Break
10:20 AM - 12:15PM	Materials & Assembly for 3D Integration by Dr Guo-Quan (GQ) Lu Thermal & Reliability Issues in 3D Integration by Dr Patrick McCluskey	MULTIPHYSICS MODELING & SIMULATION Zhenxian Liang (ORNL), Chair <i>Keynote Invited Speakers:</i> TBA (Mentor Graphics)	QUALITY & RELIABILITY Patrick McCluskey (UMD), Chair <i>Keynote Invited Speakers:</i> Craig Hillmann ()
12:15 PM 1:15 PM	Lunch - Tutorial Attendees (Networking)	Lunch (Networking)	Lunch (Networking)
1:15 PM - 3:10 PM	ADDITIVE MANUFACTURING Ola Harrysson (NCSU), Chair Govindarajan Muralidharan (ORNL), Co-Chair <i>Keynote Invited Speakers:</i> Madhu Chinthavali (ORNL)	MATERIALS Thomas Lai (Ford), Chair <i>Keynote Invited Speakers:</i> Katsuaki Suganuma (Osaka)	PASSIVE COMPONENTS Khai Ngo (VT), Chair <i>Keynote Invited Speakers:</i> Charlie Sullivan (Dartmouth)
3:10 PM - 3:35 PM	Break	Break	Break (Networking)
3:35PM - 5:30PM	THERMAL MANAGEMENT & SYSTEMS INTEGRATION Sreekant Narumanchi (NREL), Chair <i>Keynote Invited Speakers:</i> Eric Dede () Brij Singh ()	EMBEDDED COMPONENTS Paul McCloskey (), Chair <i>Keynote Invited Speakers:</i> Cian O'Mathuna () Brian Narveson (PSMA)	NCSU LAB TOURS PREES PACKAGING ADD MFG & LOGISTICS CTR
5:30 PM - 7:30 PM	WELCOME RECEPTION DIALOGUE PRESENTATIONS & VENDOR EXHIBITS	NETWORKING RECEPTION DIALOGUE PRESENTATIONS & VENDOR EXHIBITS	